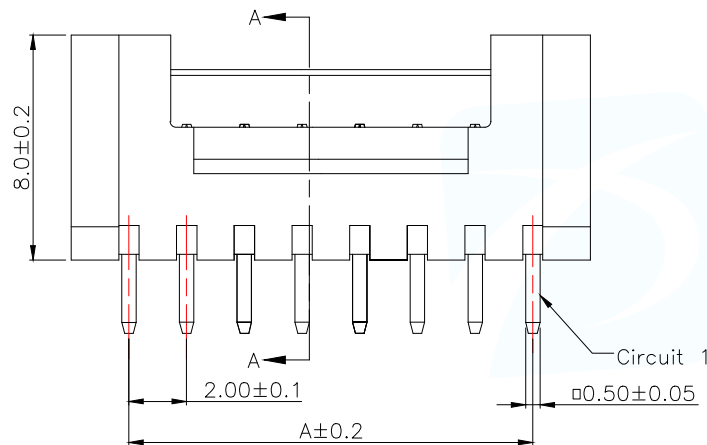
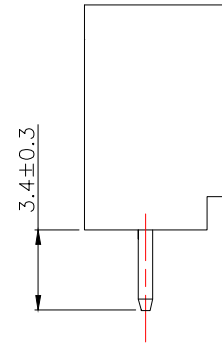
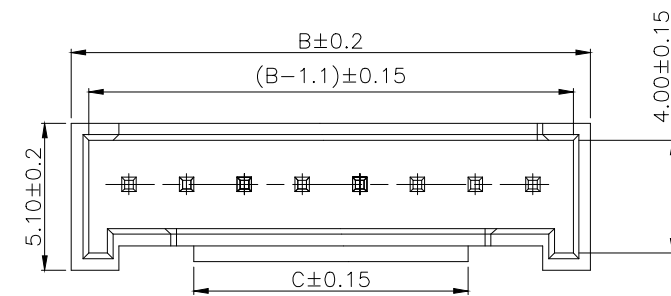
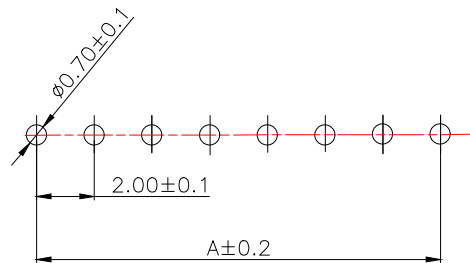


SECTION A-A

SUGGESTED PCB LAYOUT  
(COMPONENT SIDE)

技术要求:

1. 塑件材料: PA66 (UL-94V-0)
2. 接触件: 黄铜镀锡
3. 接触电阻:  $\leq 10\text{m}\Omega$
4. 绝缘电阻:  $\geq 100\text{M}\Omega$
5. 额定电压: 250V AC DC
6. 额定电流: 2.0A AC DC
7. 耐压: 能承受 1000V AC/Minute
8. 工作温度:  $-25^{\circ}\text{C} \sim +85^{\circ}\text{C}$
9. 可焊性试验: 浸锡面积  $\geq 95\%$  温度  $235 \pm 5^{\circ}\text{C}$  时间  $2.5 \pm 0.5\text{s}$
10. 铅和镉等六大有害物质含量要符合环保要求。

| Part No           | Pin | A     | B     | C     |
|-------------------|-----|-------|-------|-------|
| WAFER-HY2.0-2PZZ  | 2   | 2.00  | 6.00  | 3.00  |
| WAFER-HY2.0-3PZZ  | 3   | 4.00  | 8.00  | 3.30  |
| WAFER-HY2.0-4PZZ  | 4   | 6.00  | 10.00 | 4.00  |
| WAFER-HY2.0-5PZZ  | 5   | 8.00  | 12.00 | 6.00  |
| WAFER-HY2.0-6PZZ  | 6   | 10.00 | 14.00 | 8.00  |
| WAFER-HY2.0-7PZZ  | 7   | 12.00 | 16.00 | 10.00 |
| WAFER-HY2.0-8PZZ  | 8   | 14.00 | 18.00 | 12.00 |
| WAFER-HY2.0-9PZZ  | 9   | 16.00 | 20.00 | 14.00 |
| WAFER-HY2.0-10PZZ | 10  | 18.00 | 22.00 | 16.00 |
| WAFER-HY2.0-11PZZ | 11  | 20.00 | 24.00 | 18.00 |
| WAFER-HY2.0-12PZZ | 12  | 22.00 | 26.00 | 20.00 |
| WAFER-HY2.0-13PZZ | 13  | 24.00 | 28.00 | 22.00 |
| WAFER-HY2.0-14PZZ | 14  | 26.00 | 30.00 | 24.00 |
| WAFER-HY2.0-15PZZ | 15  | 28.00 | 32.00 | 26.00 |

|                                       |           |                                                                                                                                            |     |                                       |
|---------------------------------------|-----------|--------------------------------------------------------------------------------------------------------------------------------------------|-----|---------------------------------------|
| 2                                     | 端子Contact | 黄铜                                                                                                                                         | N*1 | 电镀(锡): 整个表面镀底镍<br>30u"MIN, 再镀锡80u"MIN |
| 1                                     | 基座Wafer   | LCP(UL94V-0)                                                                                                                               | 1   | 白色                                    |
| 序号                                    | 名称        | 材料                                                                                                                                         | 数量  | 备注                                    |
| MANUFACTURE DWG                       |           |  东莞市讯普电子科技有限公司<br>DongGuan XunPu Electronics Co., Ltd |     |                                       |
| UNLESS OTHERWISE SPECIFIED TOLERANCES |           |                                                       |     | TITLE:<br>WAFER HY2.0MM 直针            |
| DECIMALS:                             | ANGLES:   | SCALE 1:1 UNIT:MM                                                                                                                          |     |                                       |
| .X±0.20                               | ±2°       | SIZE:A4                                                                                                                                    |     |                                       |
| .XX±0.10                              |           | SHEET:1F1                                                                                                                                  |     |                                       |
| .XXX±0.05                             |           | REV:A                                                                                                                                      |     |                                       |
| CUSTOMER COPY                         |           |                                                                                                                                            |     |                                       |